

1. A polishing pad comprising:  
a first layer having a polishing surface; and  
a second layer having an adhesive region and a cured  
region disposed opposite the polishing surface.

5        2. The polishing pad of claim 1 wherein the second  
layer includes a plurality of adhesive and cured  
regions.

3. The polishing pad of claim 2 wherein the cured  
regions are circles.

10       4. The polishing pad of claim 2 wherein the cured  
regions are arc segments.

5. The polishing pad of claim 1 wherein the cured  
region and the adhesive region form concentric  
circles.

15       6. The polishing pad of claim 1 wherein a ratio of  
a surface area of the cured region to a surface area  
of the adhesive region is between about 10% to 30%.

20       7. The polishing pad of claim 1 further including a  
third layer disposed between the first and second  
layers.

8. The polishing pad of claim 1 wherein the cured  
region is partially cured.

9. The polishing pad of claim 1 wherein the cured region is entirely cured.

10. An apparatus for selectively altering the adhesive strength of a polishing pad adhesive layer,  
5 comprising:  
a radiation source to generate radiation;  
a support for the polishing pad; and  
a mask having a transparent region and an opaque  
10 region, said mask being disposed between the radiation source and the polishing pad adhesive layer, such that the radiation passes through the transparent region and is blocked by the opaque region.

11. The apparatus of claim 10 further including a shutter disposed between the radiation source and the  
15 mask.

12. The apparatus of claim 10 wherein the transparent region is an opening.

13. The apparatus of claim 10 wherein the radiation beam is ultraviolet light.

20 14. The apparatus of claim 13 wherein the transparent region is made of a UV transparent quartz or polymer material.

15. The apparatus of claim 13 wherein the mask is made of ultraviolet light blocking material.

16. The apparatus of claim 15 wherein the mask is made of metal.

17. The apparatus of claim 15 wherein the mask is made of ceramic or polymer material.

5 18. The apparatus of claim 10 wherein the transparent region and the opaque region form concentric circles.

19. The apparatus of claim 10 wherein there are a plurality of transparent regions and opaque regions.

10 20. The apparatus of claim 19 wherein the transparent regions are circles.

21. The apparatus of claim 19 wherein the transparent regions are arc segments.

15 22. A method for selectively altering the adhesive strength of a polishing pad adhesive layer, comprising:

providing a mask having a transparent region and an opaque region;

20 directing radiation toward the mask so that the radiation is blocked by the opaque region and passes through the transparent region to impinge on the adhesive layer on the polishing pad, whereby the area of the adhesive layer corresponding to the transparent region of the mask is cured to be less adhesive.

23. The method of claim 22 wherein the radiation is ultraviolet light.

24. The method of claim 23 wherein the transparent region is made of ultraviolet light transparent quartz  
5 or polymer material.

25. The method of claim 23 wherein the mask is made of ultraviolet light blocking material.

26. The method of claim 25 wherein the mask is made of metal.

10 27. The method of claim 25 wherein the mask is made of ceramic or polymer material.

28. The method of claim 25 wherein the mask is made of paper.

15 29. The method of claim 22 wherein the transparent region is an opening.

30. The method of claim 22 wherein the transparent region and the opaque region form concentric circles.

31. The method of claim 22 wherein there are a plurality of transparent and opaque regions.

20 32. The method of claim 31 wherein the transparent regions are circles.

33. The method of claim 31 wherein the transparent regions are arc segments.

34. The method of claim 22 wherein a ratio of a surface area of the cured region to a surface area of the adhesive region is between about 10% to 30%.  
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35. The method of claim 22 wherein the polishing pad is exposed to the radiation for a time between about 5 to 60 seconds.

36. The method of claim 23 wherein the radiation intensity is between about 100 to 1200 Watts/inch.  
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37. A method for selectively altering the adhesive strength of a polishing pad adhesive layer, comprising:

providing a polishing pad having a layer of adhesive that covers substantially an entire surface of the pad; and  
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curing selected portions of the adhesive layer to reduce adhesive strength of the layer.